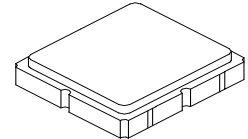


- *Hermetically sealed Surface Mount package*
- *Complies with Directive 2002/95/EC (RoHS)*

**Absolute Maximum Ratings**

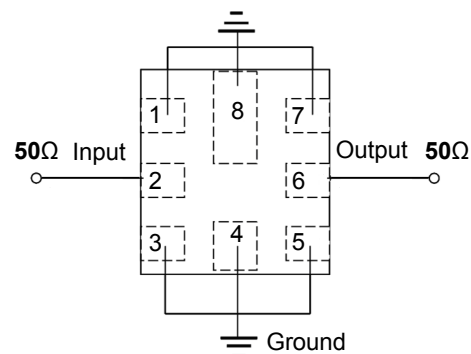
Rating	Value	Units
Maximum Input Power	10	dBm
DC Voltage	10	VDC
Operating Temperature	-40 to +85	°C
Storage Temperature	-40 to +85	°C

**SF2424D****505 MHz  
SAW Filter****SM3838-8 Case****Electrical Characteristics**

Characteristic		Sym	Notes	Minimum	Typical	Maximum	Units
Center Frequency		f <sub>C</sub>			505		MHz
Insertion Loss	500 - 508 MHz	IL			2.6	4.1	dB
	500 - 510 MHz				2.8	4.1	
Amplitude Ripple	500 - 508 MHz				0.5	2.5	dB
	500 - 510 MHz				0.6	2.5	
Attenuation (Reference level from 0dB)							dB
404 to 463.2 MHz				42	50		
544 to 604 MHz				42	48		
Temperature Coefficient of Frequency					-36		ppm/k
Terminating Source Impedance (single) Z <sub>S</sub>				50			Ω
Terminating Load Impedance (single) Z <sub>L</sub>							
Footprint Size: 3.8 X 3.8				SM3838-8			
Lid Symbolization (Y=Year, WW=week, S=shift)		B38//YWWWS					

**Electrical Connections**

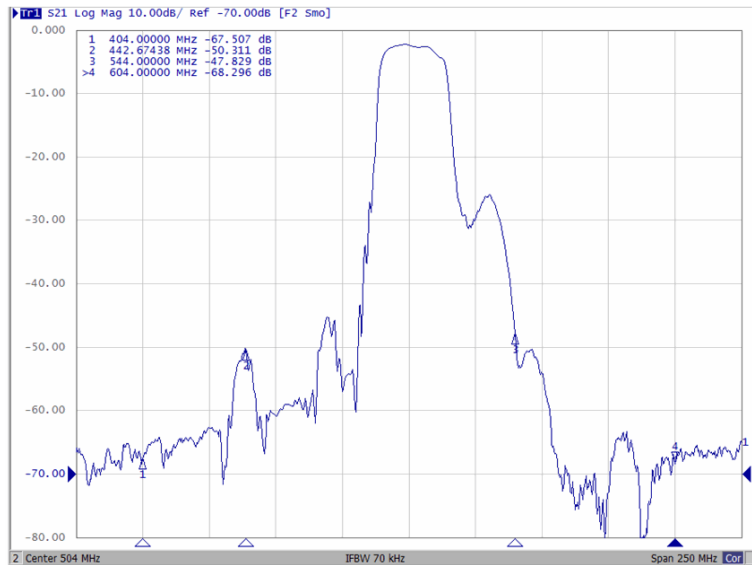
Connection	Terminals
Input	2
Output	6
Ground	All Others

**CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.****NOTES:**

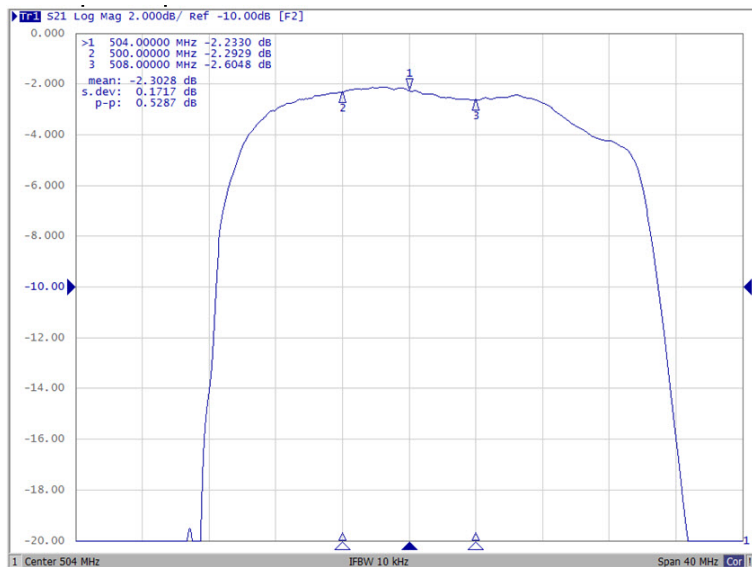
1. All specifications apply over the operating temperature range with filter soldered to the specified demonstration board unless noted otherwise.
2. Ultimate rejection is dependent on PCB layout.
3. Specifications subject to change without notice.
4. Electrostatic Sensitive Device. Observe precautions for handling.
5. US and international patents may apply.
6. Murata, stylized Murata logo, and Murata N.A., Inc. are registered trademarks of Murata Manufacturing Co., Ltd.

# Frequency Characteristics

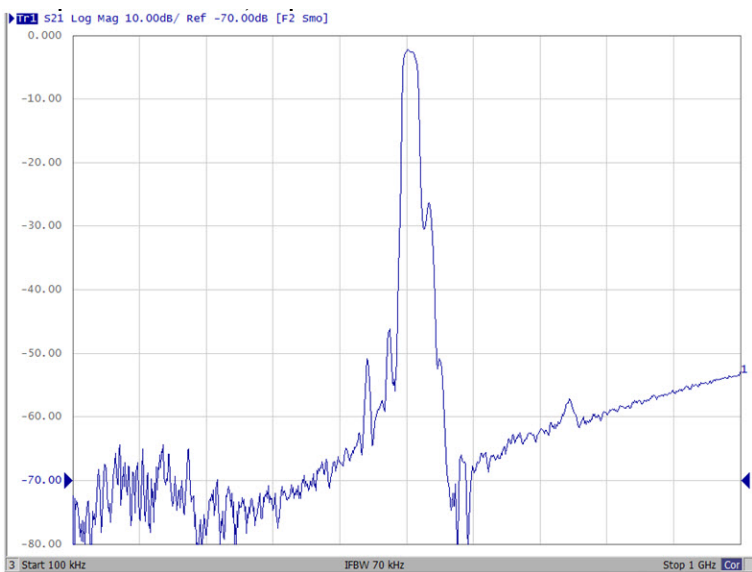
S21 Response: Center 504 MHz, Span 250 MHz



S21 Response: Span 40 MHz



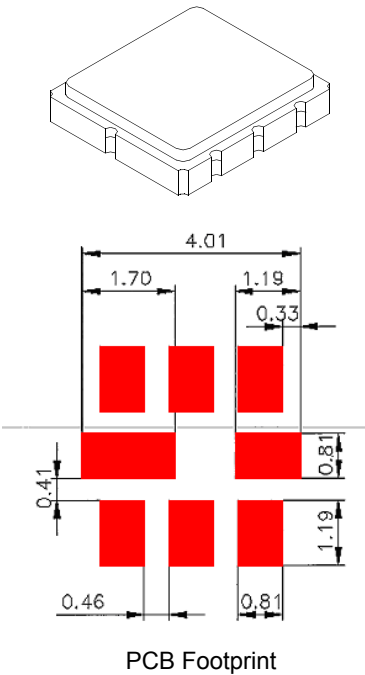
S21 Response: 0 - 1000 MHz



# SM3838-8 Case

## 8-Terminal Ceramic Surface-Mount Case

### 3.8 X 3.8 mm Nominal Footprint

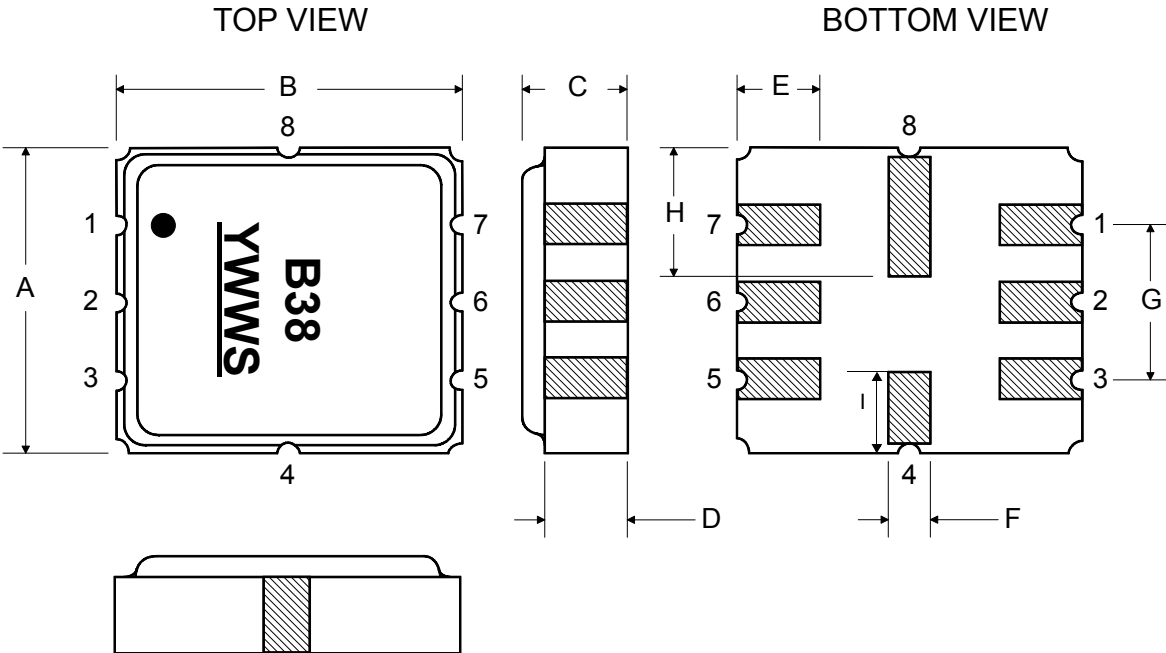


Case Dimensions						
Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	3.65	3.80	3.95	0.143	0.149	0.155
B	3.65	3.80	3.95	0.143	0.149	0.155
C	-	-	1.40	-	-	0.055
D	0.95	1.10	1.25	0.037	0.043	0.049
E	0.90	1.00	1.10	0.035	0.040	0.043
F	0.50	0.60	0.70	0.020	0.024	0.028
G	2.39	2.54	2.69	0.090	0.100	0.110
H	1.40	1.75	2.05	0.055	0.069	0.080
I	0.90	1.00	1.10	0.035	0.040	0.043

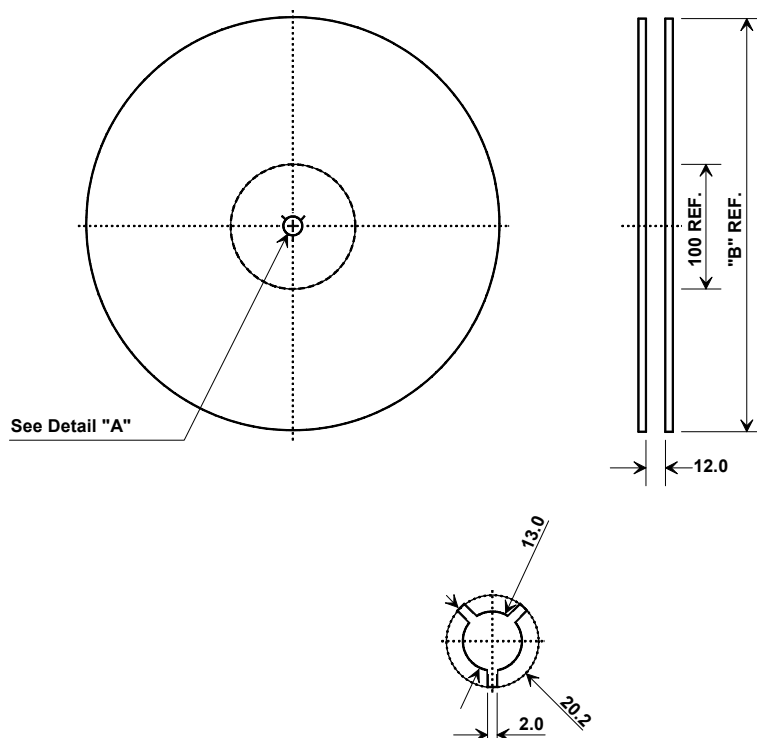
Electrical Connections		
	Connection	Terminals
Port 1	Input	2
Port 2	Output	6
	Ground	All Others

Dot Indicates Pin 1

Materials	
Solder Pad Termination	Au plating 30 - 60 μInches (76.2-152 μM) over 80-200 μInches (203-508 μM) Ni.
Lid	Fe-Ni-Co Alloy Electroless Nickel Plate (8-11% Phosphorus) 100-200 μInches Thick
Body	Al <sub>2</sub> O <sub>3</sub> Ceramic
Pb Free	



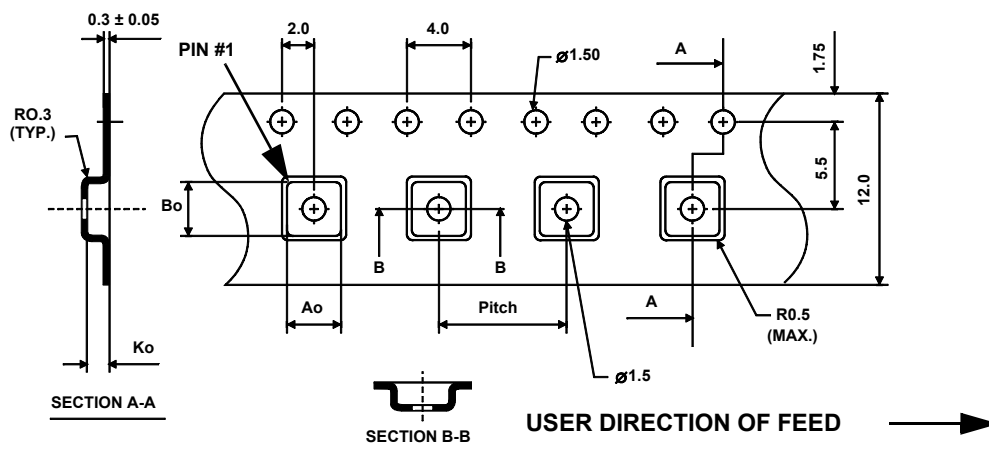
## Tape and Reel Specifications



“B “ Nominal Size		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	3000

## COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	4.25 mm
Bo	4.25 mm
Ko	1.30 mm
Pitch	8.0 mm
W	12.0 mm



# Reflow Profile

